


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/17/9975	
<b>1.3 Title of PCN</b>	Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for products in BGA package	
<b>1.4 Product Category</b>	BGA packaged products	
<b>1.5 Issue date</b>	2017-02-17	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	FRANK WOLINSKI
<b>2.1.2 Phone</b>	+49 89460062287
<b>2.1.3 Email</b>	frank.wolinski@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Michel BUFFA
<b>2.1.2 Marketing Manager</b>	Daniel COLONNA
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Materials	Any change on substrate (part number, supplier, plant, design or composition of any layer...)	Stats ChipPAC Shanghai China (SCC), Stats ChipPAC Jiangyin China (JSCC)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Current location : Stats ChipPAC Shanghai China (SCC)	Transfer from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) location. Bill Of Materials (BOM) remains unchanged. Traceability is enhanced : 2 digits are added in the marking instruction.  See more information on PCN 9975 – Additional information document attached.
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No change.	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Due to Shanghai China site closure, production is relocated to Jiangyin China site. This Product Change Notification (PCN) concerns only BGA packaged products.
<b>5.2 Customer Benefit</b>	SERVICE CONTINUITY

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Traceability is described in PCN9975_Additional information attached document
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2017-07-07
<b>7.2 Intended start of delivery</b>	2017-08-07
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	9975 PCN9975_RERMCD1624- LFBGA10x10 JSCC- MCD QA reliability plan.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2017-02-17
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<b>9. Attachments (additional documentations)</b>
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<p>9975 Public product.pdf  9975 PCN9975_Additional information.pdf  9975 PCN9975_RERMCD1624- LFBGA10x10 JSCC- MCD QA reliability plan.pdf</p>
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<b>10. Affected parts</b>
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10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F103ZEH6	
	STM32F103ZFH6	

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